

Title (en)

PLATING BATH FOR THE ELECTROLESS DEPOSITION OF SILVER AND CORRESPONDING METHOD

Title (de)

ZUSAMMENSETZUNG FÜR DIE STROMLOSE ABSCHIEDUNG VON SILBER UND ENTSPRECHENDES VERFAHREN

Title (fr)

BAIN DE PLACAGE POUR LE DÉPÔT AUTOCATALYTIQUE D'ARGENT ET PROCÉDÉ CORRESPONDANT

Publication

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Application

EP 12843616 A 20121009

Priority

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Abstract (en)

[origin: EP2772566A1] Provided are a reducing electroless silver plating solution and a reducing electroless silver plating method using the silver plating solution, the reducing electroless silver plating solution being capable of preventing decomposition of silver in the plating solution thereby to maintain stability of the solution and also being capable of preventing excessive roughening of an underlying metal or the like thereby to form a plating film having good film characteristics and a good appearance. The reducing electroless silver plating solution according to the present invention comprises a water-soluble silver salt and a reducing agent, wherein cyanide ions in a concentration of 0.006×10^{-3} mol/L to 12.5×10^{-3} mol/L are contained.

IPC 8 full level

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